P-CHANNEL POWER MOS FET FOR SWITCHING

S-90P0112SMA

The S-90P0112SMA is an P-channel power MOS FET that realizes a low on-state resistance and ultra high-speed switching characteristics. It is suitable for speeding up switching, enabling a high efficient set and energy saving. A gate protection diode is built in as a countermeasure for static electricity. Small SOT-23-3 package realize high-density mounting. This product can be driven directly by a -2.5 V power source. If use this product in combination with SII switching regulator products, you can get the highest performance.

■ Features

• Low on-state resistance: $R_{DS(on)1} = 0.27 \ \Omega \ \text{Max.} \ (V_{GS} = -4.5 \ \text{V}, \ I_D = -0.4 \ \text{A})$ $R_{DS(on)2} = 0.45 \ \Omega \ \text{Max.} \ (V_{GS} = -2.5 \ \text{V}, \ I_D = -0.4 \ \text{A})$

SOT-23-3

Ultra high-speed switching

• Operational voltage: —2.5 V drive available

Built-in gate protection diode

■ Applications

Notebook PCs

• Small package:

- Cellular and portable phones
- On-board power supplies

■ Packages

• SOT-23-3 (Package drawing code: MP003-A)

■ Item code

• Item code : S-90P0112SMA-TF

Delivery form
 Taping only

■ Pin Configuration

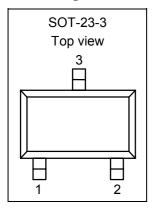


Figure 1

Table 1

Pin No.	Symbol	Description
1	G	Gate pin
2	S	Source pin
3	D	Drain pin

■ Equivalent Circuit

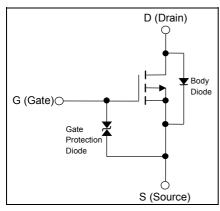


Figure 2

Caution The diode connected between the gate and source of the transistor serves as a protector against electrostatic discharge. Do not apply an electrostatic discharge to this IC that exceeds the performance ratings of the built-in gate protection diode.

And when this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

■ Absolute Maximum Ratings

Table 2

(Ta = 25°C unless otherwise specified)

		(Ta - 25 C unless	otherwise spe	cilieu)
Item /	Symbol	Conditions	Ratings	Unit
Drain to source voltage (When between gate and source short circuits)	V_{DSS}	V _{GS} = 0 V	-20	V
Gate to source voltage (When between drain and source short circuits)	V_{GSS}	V _{DS} = 0 V	±12	
Drain current (DC)	I _D		-0.7	Α
Drain current (Pulse)	I _{DP}	PW = 10 μs, Duty Cycle≤1%	-2.8	
Reverse drain current	I _{DR}		-0.7	
Power dissipation *1, *2	P_{D}		1.1	W
Channel temperature	T _{ch}		150	°C
Storage temperature	T _{stg}		-55 to +150	

Caution The absolute maximum ratings are rated values exceeding which the product could suffer physical damage. These values must therefore not be exceeded under any conditions.

- *1. Mounted on a ceramics board (1225 mm² × 1 mm)
- *2. The allowable power dissipation differs depending on the mounting form.

■ Electrical Characteristics

DC characteristics

Table 3

(Ta = 25°C unless otherwise specified)

Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
Drain cut-off current	I _{DSS}	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}$	_		-10	μΑ
Gate to source leakage current	I_{GSS}	$V_{GS} = \pm 12 \text{ V}, V_{DS} = 0 \text{ V}$	_		±10	
Gate to source cut-off voltage	$V_{GS(off)}$	$I_D = -1 \text{ mA}, V_{DS} = -10 \text{ V}$	-0.5	_	-1.2	V
Drain to source on-state resistance *1	R _{DS(on)1}	$I_D = -0.4 \text{ A}, V_{GS} = -4.5 \text{ V}$	<	0.20	0.27	Ω
	R _{DS(on)2}	$I_D = -0.4 \text{ A}, V_{GS} = -2.5 \text{ V}$		0.32	0.45	
Forward transfer admittance *1	Y _{fs}	$I_D = -0.4 \text{ A}, V_{DS} = -10 \text{ V}$		1.5		S
Body drain diode forward voltage	V_f	$I_f = -0.7 \text{ A}, V_{GS} = 0 \text{ V}$		-0.8	-1.1	V

^{*1.} Effective during pulse test (600 μ s).

Dynamic characteristics

Table 4

(Ta = 25°C unless otherwise specified)

Item	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Input capacitance	C _{iss}	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V},$	_	200		pF	Ī
Output capacitance	Coss	f = 1 MHz	_	70			
Feedback capacitance	C_{rss}			60		İ	l

Switching characteristics

Table 5

(Ta = 25°C unless otherwise specified)

Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
Turn-on delay time	t _{d(on)}	$V_{GS} = -5 \text{ V}, I_{D} = -0.4 \text{A},$	_	10		ns
Rise time	t _r	$V_{DD} = -10 \text{ V}$	_	40	_	
Turn-off delay time	t _{d(off)}			85	_	
Fall time	t _f			80	_	

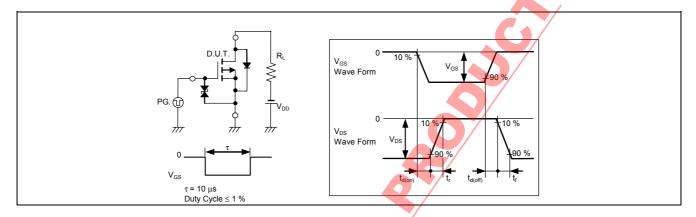


Figure 3

Thermal characteristics

Table 6

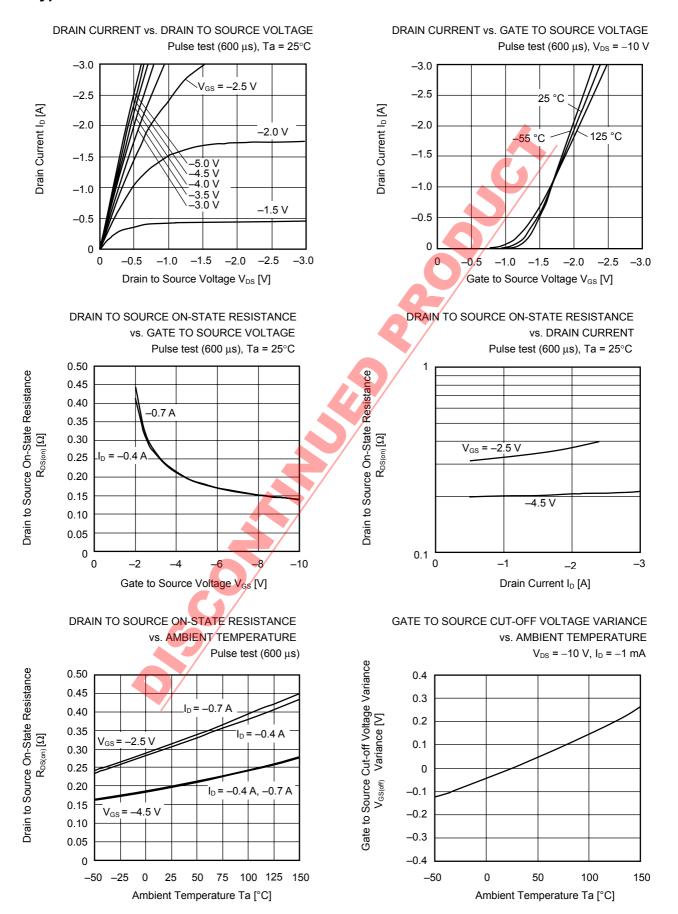
(Ta = 25°C unless otherwise specified)

Item	Symbol		Conditions	Min.	Тур.	Max.	Unit
Thermal resistance (Channel to ambience)	R _{th(ch-a)}	'/	ounted on a ceramics board 225 mm ² × 1 mm)	_	107		°C/W

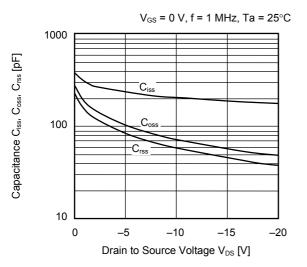
■ Precautions

- The application conditions for the input voltage, output voltage, and load current should not exceed the allowable power dissipation after mounting.
- SII claims no responsibility for any disputes arising out of or in connection with any infringement by products including this IC of patents owned by a third party.

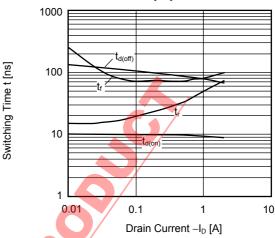
■ Typical Characteristics



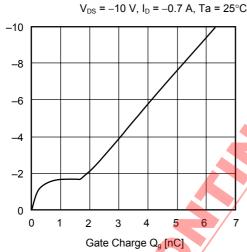
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



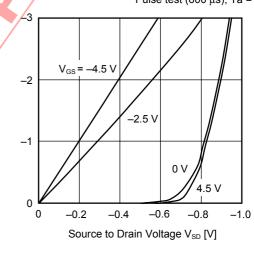
SWITCHING TIME vs. DRAIN CURRENT $V_{GS} = -5 \text{ V}, V_{DD} = -10 \text{ V}, PW = 10 \text{ }\mu\text{s},$ $Duty \text{ Cycle} \leq 1\%, \text{ Ta} = 25^{\circ}\text{C}$



GATE TO SOURCE VOLTAGE vs. GATE CHARGE

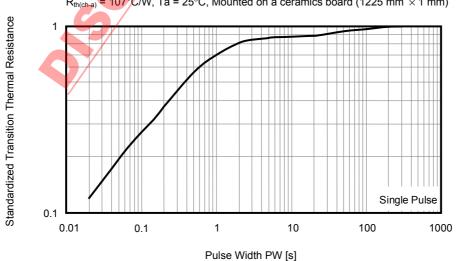


REVERSE DRAIN CURRENT vs. SOURCE TO DRAIN VOLTAGE
Pulse test (600 µs), Ta = 25°C



STANDARDIZED TRANSITION THERMAL RESISTANCE vs. PULSE WIDTH $R_{th(ch-a)} = 107^{\circ}$ C/W, Ta = 25°C, Mounted on a ceramics board (1225 mm² × 1 mm)

Reverse Drain Current Log [A]



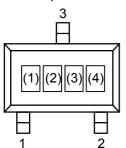
Gate to Source Voltage V_{GS} [V]

■ Marking Specification

SOT-23-3 Top view

(1)~(3) : Product code (Refer to **Product name vs. Product code**)

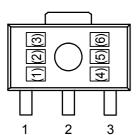
(4) : Lot number



Product name vs. Product code

Product name	Product code				
Floduct flame	(1)	(2)	(3)		
S-90P0112SMA-TF	0	N	S		

SOT-89-3 Top view



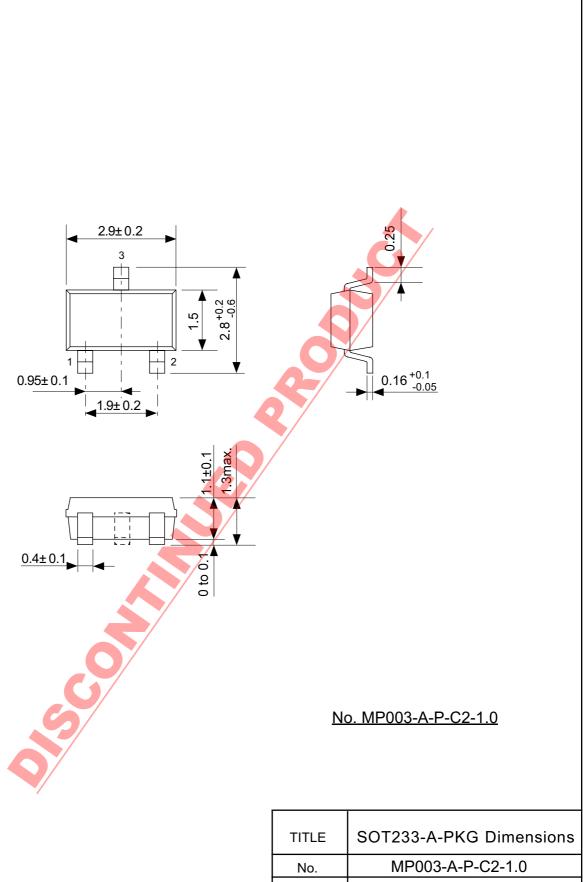
(1)~(3) : Product code (Refer to **Product name vs. Product code**)

(4)~(6) : Lot number

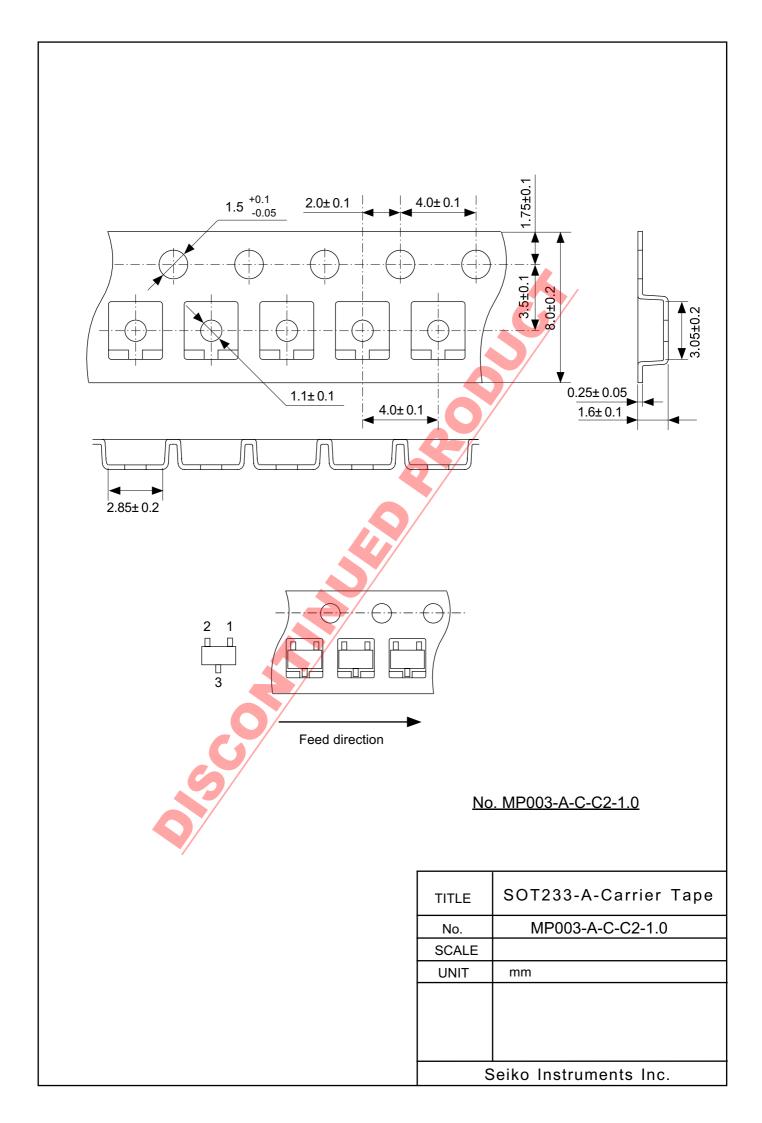
Product name vs. Product code

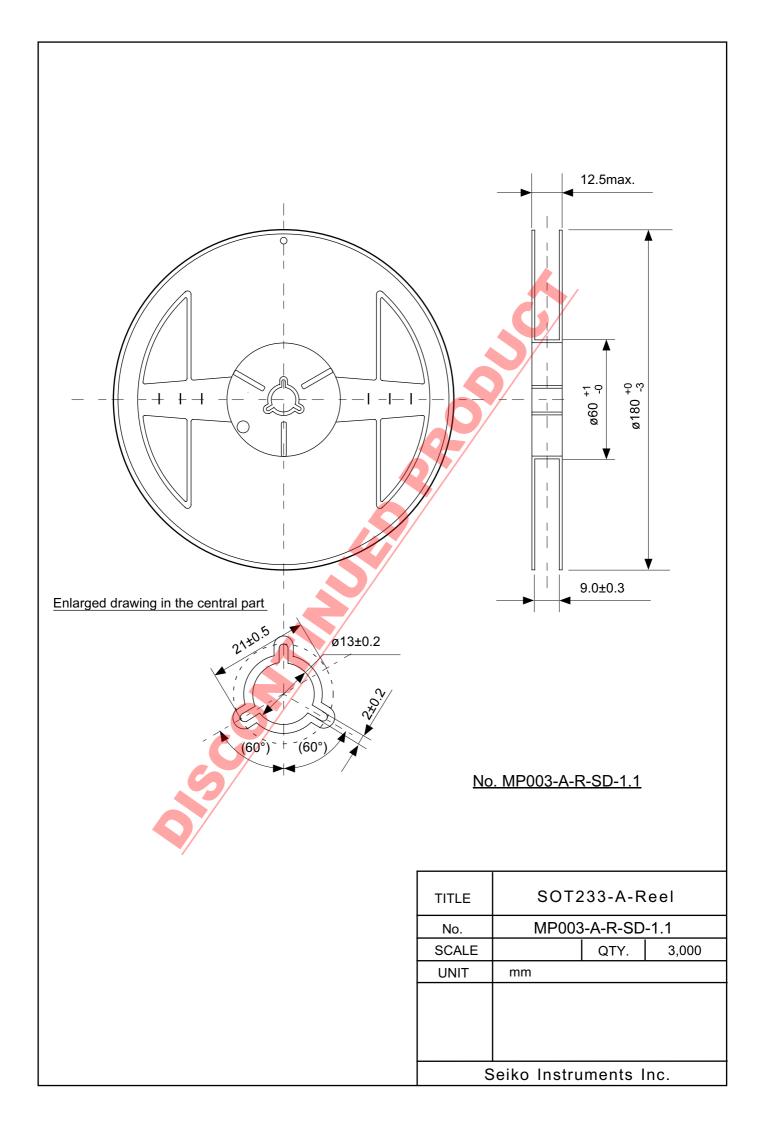
Product name	Product code			
1 Toddet Harrie	(1)	(2)	(3)	
S-90P0222SUA-TF	0	N	W	
S-90P0332SUA-TF	0	N	Х	

Remark The mark ★ shows the product indicated in this data sheet.



TITLE	SOT233-A-PKG Dimensions
No.	MP003-A-P-C2-1.0
SCALE	
UNIT	mm
S	Seiko Instruments Inc.







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